

-Copper Clad Laminate-"3layer FCCL"

Example of use

- Mobile devices (mobile phone, Tablet PC and others)
- · HDD · DSC
- Substrate for LED · For automobile applications

Characteristics

- FCCL with internally designed polyimide resin coated on base film such as polyimide, and laminated copper foil.
- Product design with unique characteristics are available as per customer request by changing base material and copper foil.

Product structure

- Metal foil (copper, aluminum or others)
- Insulation adhesive
- Insulation base film (polyimide or PET film)

*****Double-sided FCCL is also available.

Product Properties

Item		Condition	Unit	LC	LE(P)	LCB	L60R	LSPGS
Characteristic		Ι	I	For general purpose	High Tg	Black	White	Transparent adhesive
Product structure		_	Ι	Copper foi Adhesive Polyimide		Copper fo Adhesive Polyimide	1	Electrodeposited Adhesive PET film Special coating
180° Peel strength	MD	Normal state	N/cm	11.0	7.5	9.0	10.0	8.0
Dimensional stability	0.5hr/ 150℃	MD	%	-0.08	-0.15	-0.15	-0.10	*-0.18
		TD		+0.08	+0.02	+0.08	-0.05	*0.06
Solder heat resistance		-	°C	300	300	300	300	190
Adhesive Tg		-	°C	42	143	42	50	30
Adhesive elasticity		Norma state	GPa	0.3	4.0	0.4	1.5	0.7

*****Double-sided structures are also available.

***0.5hr/125**℃

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